PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Seung Taek YANG	06/29/2007

RECEIVING PARTY DATA

Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si
City:	Kyoungki-do
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11777368

CH $40.00 11777368

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	CU-5790 WWP/DS
NAME OF SUBMITTER:	Woochoon W. Park

Total Attachments: 2
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UNITED STATES OF AMERICA

ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:
Name : Seung Taek YANG
Address : 103-1703, Daedong Hwangtobang Apts., 581-606, Sanggye 2-dong, Nowon-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:
Name : Hynix Semiconductor Inc.
Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE

(TITLE)

and which is found in *(check one applicable item below)*

☑ U.S. patent application executed on even date herewith

☐ U.S. Application Serial No. ______________ filed on ______________

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

June 29, 2007.
Date

Seung Taek Yang
INVENTOR: Seung Taek YANG

0699P/1